



Product End-of-Life Disassembly Instructions

Product Category: Networking Equipment

Marketing Name / Model

[List multiple models if applicable.]

HP A-F5000 Firewall Chassis (JG216A)

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	8
Batteries	All types including standard alkaline and lithium coin or button style batteries	0
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		2
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		10
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Screw driver	2#

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Unscrew the screws on mounting angle 2, and then remove mounting angle 2 from the chassis.
2. Remove film 3 from plastic panel 4.
3. Remove film 5 from plastic panel 4.
4. Remove plastic panel 4 from the chassis.
5. Unscrew the screws on front panel 6, and then remove front panel 6 from the chassis.
6. Unscrew the screws on front panel 7, and then remove front panel 7 from the chassis.
7. Remove film 8 from the chassis.
8. Unscrew the screws on front panel 9, and then remove front panel 9 from the chassis.
9. Unscrew the screws on blank filler panel 10, and then remove blank filler panel 10 from the chassis.
10. Unscrew the screws on power module 11, and then remove power module 11 from the chassis.
11. Unscrew the screws on blank poe module panel 12, and then remove blank poe module panel 12 from the chassis.
12. Unscrew the screws on blank power module panel 13, and then remove blank power module panel 13 from the chassis.
13. Unscrew the screws on fan frame 14, and then remove fan frame 14 from the chassis.
14. Unscrew the screws on back cover 15, and then remove back cover 15.
15. Unscrew the screws on rib 17, and then remove rib 17 from the chassis.
16. Unscrew the screws on PCB 16, and then remove PCB 16.
17. Remove shielding finger 6-2 from front panel 6-1.
18. Unscrew the screws on pcb 6-3, and then remove pcb 6-3 from front panel 6-1.
19. Unscrew the screws on pcb 6-4, and then remove pcb 6-4 from front panel 6-1.
20. Unscrew the screws on pcb 6-5, and then remove pcb 6-5 from front panel 6-1.
21. Unscrew the screws on pcb 6-6, and then remove pcb 6-6 from front panel 6-1.
22. Remove film 6-7 from front panel 6-1.
23. Remove shielding finger 7-3 from front panel 7-1.
24. Unscrew the screws on pcb 7-2, and then remove pcb 7-2 from front panel 7-1.
25. Remove film 7-4 from front panel 7-1.
26. Unscrew the screws on pcb 7-5, and then remove pcb 7-5 from front panel 7-1.
27. Remove shielding finger 10-2 from blank filler panel 10-1.
28. Remove film 10-3 from front panel 10-1.
29. Unscrew the screws on PCB 14-2, and then remove PCB 14-2 from fan frame 14-1.
30. Remove film 14-3 from fan frame 14-1.
31. Remove shielding finger 14-4 from fan frame 14-1.
32. Unscrew the screws on fan 14-5, and then remove fan 14-5 from fan frame 14-1.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

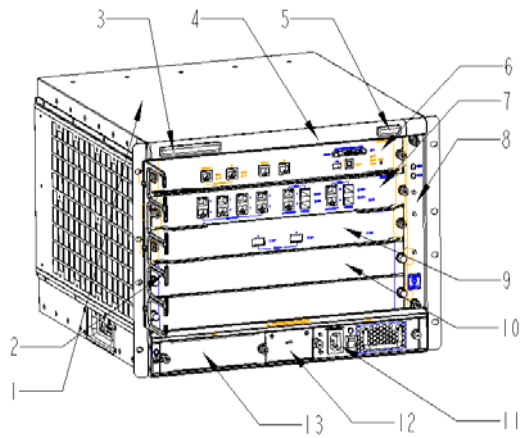


Figure 1 Treatments to the product (front view)

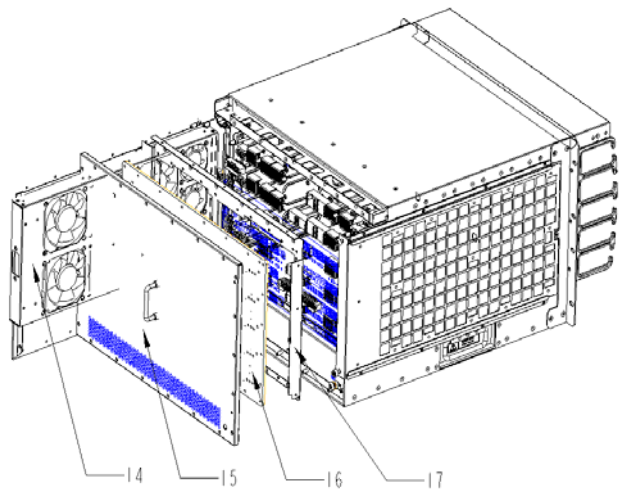


Figure 2 Treatments to the product(rear view)

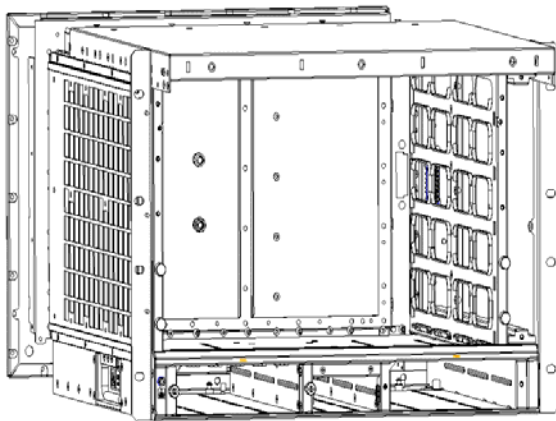


Figure 3 Part 1

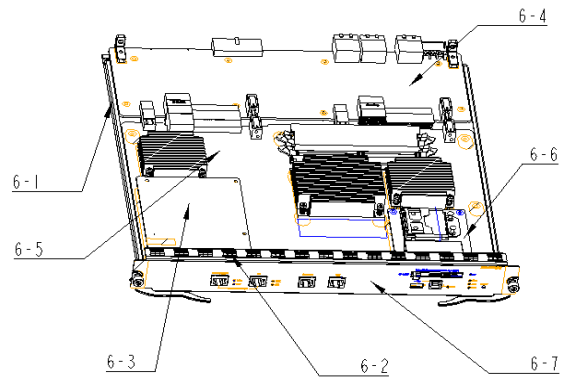


Figure 4 Treatments to front panel 6

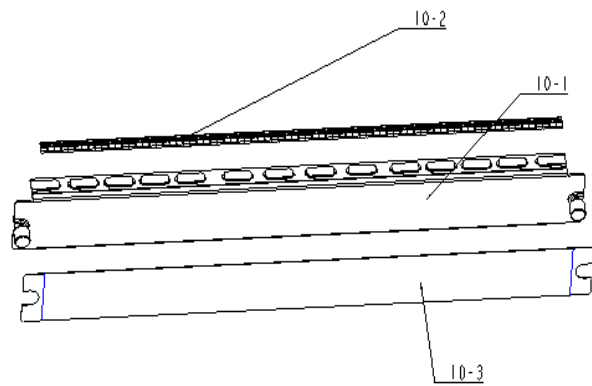
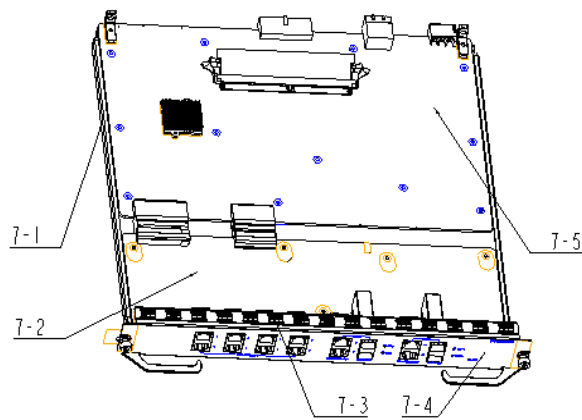


Figure 5 Treatments to front panel 7

Figure 6 Treatments to blank filler panel 10

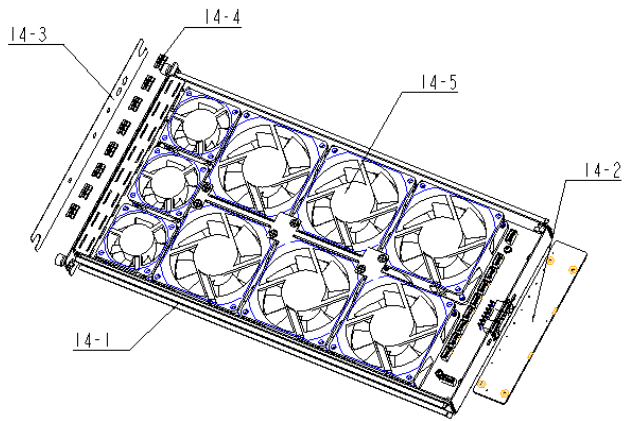


Figure 7 Treatments to fan frame 14